



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260713000.1	PCN Issued	July 22, 2026
Qualification of RFAB site and Die revision for select devices		Sample request deadline:	September 20, 2026
		Estimated 1st ship date:	October 20, 2026
Sample requests received after September 20, 2026 will not be supported.			

Change type(s)
Assembly Material
Design
Packing/Shipping/Labeling
Wafer Fab Site
Wafer Fab Material
Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC9PLV qualified process technology, die revision, and datasheet update for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SFAB	JI	150mm	RFAB	LBC9PLV	300mm

The die was also changed as a result of the process change.

Construction Differences are as follows:

	Current	Proposed
Bond wire material / diameter	Cu; 1.98 mil	Cu; 1.3 mil
Mold compound/encapsulation material	SID#R-28	SID#R-46

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history shown below. The links to the revised datasheets are available in the table below.



TL1963A, TL1963A-15, TL1963A-18, TL1963A-25, TL1963A-33

SLVS719H – JUNE 2008 – REVISED JUNE 2026

Changes from Revision G (January 2015) to Revision H (June 2026)	Page
• Updated the <i>Features</i> section to include comparison between Legacy and New chip performance (input, output range, output voltage accuracy and package thermal details).....	1
• Updated Absolute maximum ratings, ESD, Recommended Operating Conditions, Thermal and Electrical Characteristics tables to show performance comparison between legacy and new chip.....	5
• Updated Overview section to highlight key features of legacy and new chip.....	24

- Updated *Overload Recovery*, *Output voltage noise* and *Protection features* section for comparison between legacy and new chip and better readability to customers and added details about *SHDN*, *Undervoltage Lockout (UVLO)*, *Thermal shutdown* and *Current limit* sections.....24
- Updated Protection Features to create For Legacy Chip Only and For Both Legacy and New chip sections. 27
- Updated *Device Functional Modes* section for better readability of the datasheet.....28
- Updated Application Information sections for better datasheet readability and added *Reverse Current*, *Feed-forward Capacitor*, *Estimating Junction Temperature* and *Power Dissipation (P_D)* sections..... 29
- Updated Typical Applications section for better readability and comparison between legacy and new chip... 31
- Added Load and Line Transient plots for Legacy and New chip in the *Application curve* section.....33
- Moved Power Supply Recommendations to Application and Implementation section.....36
- Moved Layout to Application and Implementation section.....37
- Added Device support section and updated EVM details for TL1963A-xx devices.....42
- Added Device nomenclature section with details about legacy and new chip.....42

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
TL1963A	SLVS719G	SLVS719H	http://www.ti.com/product/TL1963A

Qual details are provided in the Qual Data Section.

Reason for Change: Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability:

- These devices include new die with schematic or behavior changes.
- There are changes in the electrical tables.
- Physical aspects of the device have changed.
- Review updated datasheets and/or the Standard Data Packet for more details on the changes. Evaluating samples is encouraged.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information

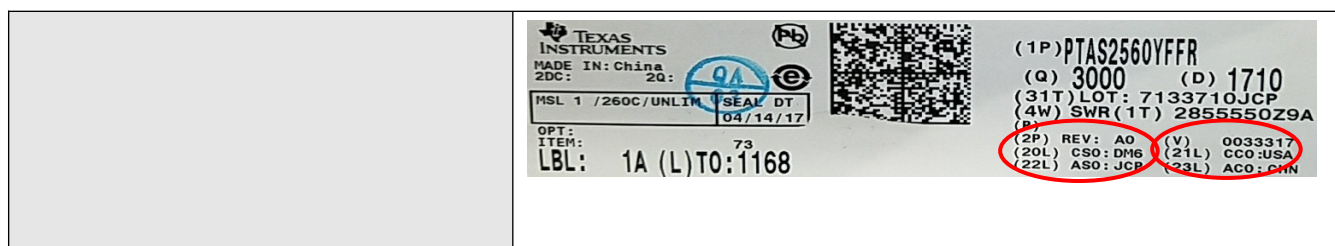
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SFAB	SHE	USA	SHERMAN
RFAB	RFB	USA	Richardson

Die Rev:
Current

New

Die Rev [2P]	Die Rev [2P]
D	A

Sample product shipping label (not actual product label):



Products Affected:

TL1963A-18DCYR TL1963A-33DCYR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TL1963A-33DCYR	QBS Process Reference: TPS25221DBVR	QBS Package Reference: TLV761D5DCYR	QBS Package Reference: TPS7B8350QDCYRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	1/77/0	-	3/231/0	3/240/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	3/231/0	3/240/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	3/231/0	3/240/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/50/0
HTOL	B1	Life Test	140C	480 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0

Type	#	Test Name	Condition	Duration	Qual Device: TL1963A-33DCYR	QBS Process Reference: TPS25221DBVR	QBS Package Reference: TLV761D5DCYR	QBS Package Reference: TPS7B8350QDCYRQ1
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0
ESD	E2	ESD CDM	-	1500 Volts	1/3/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TL1963A-33DCYR is qualified at MSL2 260C
- Qual Device TL1963A-33DCYR is qualified at MSL2 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2404-043

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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